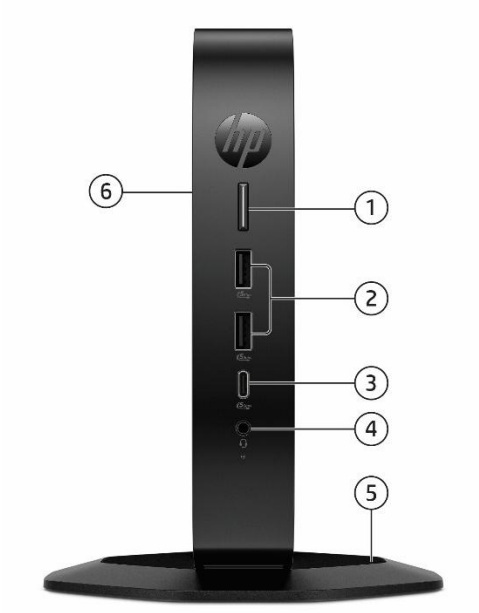
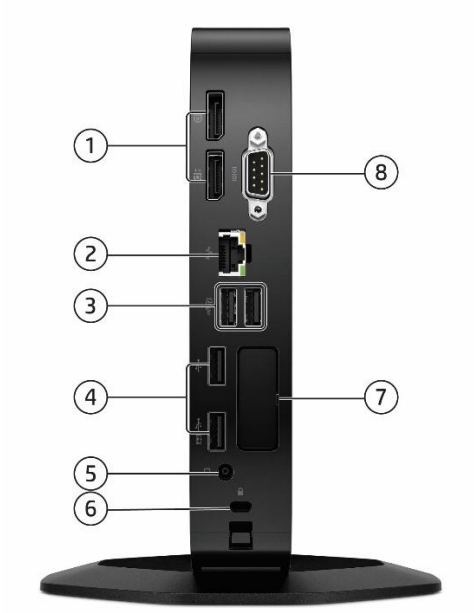
Overview

HP ProDesk 5 G1i Thin Client





FRONT

1. Power Button
2. (2) USB-A 3.2 Gen1 (5Gbps signaling rate)
3. (1) USB-C® 3.2 Gen1 (5Gbps signaling rate)
4. 3.5mm Universal Audio Jack
5. System stand
6. 100 x 100mm VESA mounting holes

BACK

1. (2) DisplayPort™ 1.4
2. (1) LAN (RJ45) (10/100/1000Mbps)
3. (2) USB-A 3.2 Gen2 (10Gbps signaling rate)
4. (2) USB-A 2.0 (480Mbps)
5. DC 4.5mm
6. Cable Lock support
7. Configurable Option Port supporting one of the following:
   - VGA
   - HDMI 2.0b
   - 2 x USB-A 3.0 Gen1 (5Gbps signaling rate)
   - USB-C DisplayPort™ over USB-C® 3.2 Gen 2 with USB 100W Power Delivery
   - External Wi-Fi® antenna
   - Serial port
   - No optional port
8. (1) Serial port (optional)

Overview

AT A GLANCE

- Intel® N N97 (12W) Quad-Core Processor, 6MB Cache, up to 3.60 GHz (4 cores)
- DDR5 single channel SDRAM system memory; up to 4800 MT/s transfer rate; 1 SODIMM slot
- 2 x DisplayPort™ 1.4 video outputs supporting up to UHD/4K (3840 x 2160@60 Hz) resolutions. N50 (6W) Dual-Core Processor supports two native DisplayPorts and does not support rear flex I/O option. N97 Quad-Core Processor supports Optional DisplayPort over USB-C port to support up to three displays.

  NOTE: DisplayPort™ cables and displays sold separately.
- Up to 512GB flash memory; non-volatile; M.2 form factor module
- RJ45 Gigabit Ethernet (GbE) network connection
- Optional Wi-Fi® 6 Intel AX211 (Internal Antenna) or 6E AX211(External Antenna) + Bluetooth® 5.3; Mediatek RZ616 Wi-Fi® 6 (Internal Antenna) or RZ616 6E (External Antenna) + Bluetooth® 5.3

  NOTE: Wireless features, performance and support may vary depending on environmental variables such placement, settings and firmware of your access points. Please contact your wireless vendor for support of your wireless environment
- Option Port with a selection of available factory options (see detailed listing later in this document)
- 3.5 mm combo headset audio jack
- 65W non-PFC external power adapter
- TPM version 2.0 (available with WIN 11 IoT system); UEFI (BIOS), cable lock slot
- Passive thermal design (no cooling fans) and active thermal management technology that monitors the system operating temperatures, throttles SOC operation if appropriate and prevents unit thermal shutdown.
- Rated for a maximum ambient operating temperature of 40 degree C
- ENERGY STAR® certified and EPEAT® Silver registered in the United States. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit www.epeat.net for more information.
- Post-consumer recycled plastics content 50% total unit plastics (by weight)
- Low halogen material content

NOTE: See important legal disclosures for all listed specs in their respective features sections.

WARRANTY

HP one-year hardware limited warranty in most regions; HP Care Packs* are extended service contracts that go beyond your standard limited warranties; for more details visit http://www.hp.com/go/cpc

*HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP Services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Technical Specifications

OPERATING SYSTEMS

- HP ThinPro, including HP Smart Zero Core
- Windows 11 IoT Enterprise LTSC 2024*
- IGEL OS

*Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com .

PROCESSOR[1]

Model	CPU Frequency Max/Base	Cores/Threads	GPU Type	GPU Frequency
Intel® Processor N-series N97 (12W)® Quad-Core Processor	3.60GHz/2.0 GHz	4/4	Intel® UHD Graphics[2]	850 MHz

[1] Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

[2] Graphics chipset uses part of the total system memory (RAM) for graphics performance. System memory dedicated to graphics performance is not available for other use by other programs.

DISPLAY SUPPORT

Number of displays supported: A maximum of 3 displays are supported with Intel® Processor N-series N97 (12W)® Quad-Core Processor; Up to 3x 4K@60Hz simultaneous displays with Optional I/O purchase

Video outputs:

Standard: (2) DisplayPort™ 1.4 (onboard)

Optional: (1) DisplayPort™ over USB-C® with USB Power Delivery
(1) VGA analog output
(1) HDMI 2.0b digital output

NOTE: adding an optional output does not increase the number of displays supported for Intel® Processor N-series N50 (6W)® Dual-Core Processor.

Max. screen resolution: DP and HDMI max: 3840x2160
VGA max: 2048x1152@50Hz / 1920x1080

	N97
1 Monitor	1 x 4K@60Hz
2 Monitor	2 x 4K@60Hz
3 Monitor	3 x 4K@60Hz

Technical Specifications

Windows 11 Enterprise 2024 *Min of 8GB required	**≤2 x 1080p FHD (1920x1080) 60Hz**	**1 x 4K UHD (3840x2160) 30Hz**	**2 x 4K UHD (3840x2160) 30Hz**	**1 x 4K UHD (3840x2160) 60Hz**
Static screen (no video)	√	√	√	√
Play 1080p 60fps (or below) video	√	√	√	√
4K 30fps video	√	√	√	√
4K 60fps video	√	√	√	√

ThinPro 9.0	**≤2 x 1080p FHD (1920x1080) 60Hz**	**1 x 4K UHD (3840x2160) 30Hz**	**2 x 4K UHD (3840x2160) 30Hz**	**1 x 4K UHD (3840x2160) 60Hz**
Static screen (no video)	√	√	√	√

Note:
Simultaneous displays are configuration dependent
N50 SKUs do not support all 4K video files/streaming

MEMORY

Type: DDR5 Single Channel SODIMM

Data Transfer Rate: Up to 4,800 MT/s

Number of Slots 1 x SODIMM 8GB, 16GB

Capacities: 8GB, 16GB*

NOTE: 8GB Min required for Windows 11

NOTE: The system's Graphics Processing Unit (GPU) uses part of the total system memory. System memory dedicated to graphics performance is not available for use by other programs.

Technical Specifications

UEFI

UEFI Specification Revision	2.9 (or newer)
TPM 2.0	Meets requirements for Common Criteria, an independent third-party certification of trustworthiness. Meets requirements for FIPS 140-2, a standard for cryptographic integrity.
Security features	System UEFI designed to address NIST SP 800-147 BIOS protection guidelines and NIST SP800-155 BIOS integrity measurement guidelines.

STORAGE*

Type:	NAND flash memory; non-volatile
Number of Sockets:	1 x M.2
Capacities:	32 GB M.2 eMMC Flash Memory 64 GB M.2 eMMC Flash Memory 256 GB M.2 PCIe NVMe Flash Memory 512 GB M.2 PCIe NVMe Flash Memory

NOTE 32GB & 64GB eMMC used in special eMMC connector, NVMe can be used in the M.2
NOTE 64GB min. Storage for Windows 21H2

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB (for Windows) is reserved for system recovery software.

INPUT/OUTPUT

	Front access:	(2) USB-A 3.2 Gen 1 (5Gbps signaling rate) (1) USB-C® 3.2 Gen 1 port (5Gbps signaling rate) (1) 3.5mm Universal Audio Jack
	Rear access:	(2) DisplayPort™ 1.4 (1) Serial Port (1) RJ45 1Gb Ethernet (10/100/1000 Mbps) (2) USB-A 3.2 Gen2 (10Gbps signaling rate) (2) 1xUSB-A 2.0 (1) Optional Port (1) DC Jack Cable Lock support
Video Outputs:	Standard:	(1) VGA analog output
	Optional:	(1) HDMI output (1) USB-3.0 (1) USB-C (1) External Antenna
I/O Interfaces:	Standard:	(1) RJ45 1Gb Ethernet (Rear) (1) 3.5 mm universal audio jack (front)

Option Port: The rear I/O panel includes an Option Port that can be configured with one of the following factory options:

- VGA
- External Wi-Fi® antenna
- HDMI

- 2x USB-A 3.0 Gen1(5Gbps signaling rate)
- DisplayPort™ over USB-C® with USB Power Delivery
- Serial port
- No optional port

AUDIO/VIDEO

Audio

- Integrated PC speaker for basic audio playback
- 3.5 mm headset audio port on front supporting headphones, headset, external speaker systems, or microphone.
- Realtek ALC3252 high definition audio Codec; 4-channel DAC supports 16/20/24-bit PCM for independent stereo sound output (streaming playback); the 4-channel ADC supports 16/20/24-bit
- PCM format for two stereo and independent analog sound inputs; incorporating Realtek converter technology achieves a 97dB dynamic range playback quality and a 90dB dynamic range recording quality. It meets WLP (Windows Logo Program) requirements for Windows systems.

Video CODECs

- MPEG-4 part 2 (DivX, Xvid)
- MPEG-4 part 10 (H.264, AVC), Advanced Video Coding (AVC) (H.264 encode)
- MPEG-H part 2, High Efficiency Video Coding (HEVC) (H.265 decode)
- WMV 7/8/9 VC-1 & ASF Demuxer
- Includes hardware acceleration support

HARDWARE SECURITY

- Security lock support (cable lock sold separately)
- Trusted Platform Module 2.0

NETWORKING

Local Area Networking	Realtek RTL8111HSH-CG Gigabit Ethernet 1 (GbE) Controller
Wi-Fi® Networking	Intel AX211 Wi-Fi 6E + Bluetooth® 5.3 WLAN[1,2] Mediatek RZ616E Wi-Fi6E +Bluetooth®5.3 WLAN[1,2]

NOTES:

[1]Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs.

[2]Wi-Fi 6E requires a Wi-Fi 6E router, sold separately to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

Wireless features, performance and support may vary depending on environmental variables such placement, settings and firmware of your access points. Please contact your wireless vendor for support of your wireless environment

Non-volatile Storage:

The MAC address is unique for each system; assigned from the board assembly manufacturer's IEEE registered allocation.

The PCI subsystem ID is unique to HP and unique to each design to allow Windows Update to be finely controlled.

Technical Specifications

SOFTWARE SUPPORT

Host Environment	Protocol	HP	Microsoft
		ThinPro 9.0	Windows 11 IoT Enterprise 2024
Remote Desktop Services	Remote FX (RFX), RDP	✓	✓
Citrix®	ICA, HDX	✓	✓
VMware® Horizon	RDP, PCoIP, Blast Extreme	✓	✓

Protocol Clients	HP	Microsoft
	ThinPro 9.0	Windows 11 IoT Enterprise 2024
Citrix® Workspace app	✓	✓
Microsoft Remote Desktop Client		✓
Free Remote Desktop Client	✓	
VMware™ Horizon View™ Client	✓	✓
HP Remote Graphics Software (RGS)	via add-on	✓
Turbosoft TTerm for Linux® Terminal emulation Software	via add-on	
Turbosoft TTWin Terminal emulation software		via add-on
AVD/Win365	via add-on	via add-on
AWS Amazon Workspace	via add-on	via add-on
HP Anyware[1]	via add-on	via add-on

[1]HP Anyware supports Windows®, Linux® and MacOS® host environments and Window, Linux, MacOS, iOS®, Android®, and Chrome OS® end-user devices. For more on the system requirements for installing HP Anyware, refer to the Admin Guides at: Find your component | HP Anyware Documents and Downloads

Browser Support	HP	Microsoft
	ThinPro 9.0	Windows 11 IoT Enterprise 2024
Mozilla Firefox	✓	
Microsoft Edge		✓
Google Chrome	✓	via online download

Technical Specifications

Security	HP	Microsoft
	ThinPro 9.0	Windows 11 IoT Enterprise 2024
Smart Card (external smartcard reader required)	✓	✓
Log-on Manager	✓	✓
Read only Operating System	✓	✓
802.1x	✓	✓
Microsoft Firewall		✓
HP Write Manager[1]		✓
Microsoft Unified Write Filter		✓
Encrypted file system (select w/ customer set up)	✓	
ThinPro signing solution	✓	

[1]The HP Write Manager is the default active write filter. The Microsoft Unified Write Filter is disabled by default but can be enabled by the user if required.

Management Tools	HP	Microsoft
	ThinPro 9.0	Windows 11 IoT Enterprise 2024
HP Wolf Cloud Endpoint Manager[1]	✓	✓
HP Device Manager[2,3,4,5]	✓	✓
HP ThinUpdate[2,3,4]		✓
HP Easy Tools[2,3,4]	✓	
HP Smart Zero Client Services[2,3,4]	✓	
Microsoft SCCM/EDM agent[2,3,4]		✓
HP USB Port Manager		✓
HP User State Tool		Add-on only
ThinPro Connection Manager	✓	
ThinPro Snapshot	✓	

Technical Specifications

[1]HP Wolf CEM requires Windows 10 IoT Enterprise LTSC 2019 or later or HP ThinPro 8.0 operating system or later on endpoint and Internet access. Visit https://www.hp.com/us-en/solutions/cloud-computing/thin-client-software.html to download or view the complete details, features and configuration requirements.
[2]Requires installation and download from HP.com .
[3]Requires Windows 10 IoT Enterprise LTSC 2016 orlater or HP ThinPro 7.2 SP11 operating system orlater on endpoint and Internet access. Visit https://www.hp.com/us-en/solutions/cloudcomputing/thin-client-software.html to download or view the complete details and configuration requirements. See datasheet for feature listings as they become available at the following URL: https://www8.hp.com/h20195/v2/GetDocument.aspx?docname=c08045808.
[4]Software is dependent on operating system installed.
[5]Internet access required and sold separately.

Additional Windows Components	HP	Microsoft
	ThinPro 9.0	Windows 11 IoT Enterprise 2024
HP Smart Shell[1,2,3,4]		✓
Windows Media Player		✓
Microsoft Direct Access		✓
Microsoft BranchCache		✓
Microsoft AppLocker		✓
Microsoft Sideloading		✓
CyberLink Media Player		✓
Microsoft BitLocker		✓

NOTE: Other add-on software available (see: http://www.hp.com/support for latest list of available add-ons). Software performance and support may vary depending on customer environment and backend.

[1]HP Smart Shell is currently available on HP Thin Clients with a Windows Embedded OS.
[2]Requires installation and download from HP.com .
[3]Requires Windows 10 IoT Enterprise LTSC 2016 orlater or HP ThinPro 7.2 SP11 operating system orlater on endpoint and Internet access. Visit https://www.hp.com/us-en/solutions/cloudcomputing/thin-client-software.html to download or view the complete details and configuration requirements. See datasheet forfeature listings as they become available at the following URL: https://www8.hp.com/h20195/v2/GetDocument.aspx?docname=c08045808.
[4]Software is dependent on operating system installed.

Audio/Video CODECs	HP	Microsoft
	ThinPro 9.0	Windows 11 IoT Enterprise 2024
MP3	✓	✓
WMA stereo	✓	✓
AAC stereo & HE AAC	✓	
Microsoft AC3 encoder		✓
MPEG-1	✓	

Technical Specifications

MPEG-4 part 2 (DivX, Xvid, H.263)	✓	✓

MPEG-4 part 10 (H.264, AVC)	✓	✓
WMV 7/8/9/ VC-1 & ASF Demuxer	✓	✓

Recommended TC config for Microsoft Teams media optimization			
	TC CPU	**VMware Teams Optimization**	**Citrix Teams Optimization**
ProDesk 5 G1	2.00 GHz 4 Core	✓	✓
- Not recommended, ✓ recommended			

WEIGHTS & DIMENSIONS

W x D x H: (vertical orientation)	35 x 200 x200 mm; (1.38 x 7.87 x 7.87 in.)
Volume:	1.2 liter
System Weight (unit with stand)	1019g
Shipping Weight	2,879g

NOTE: All measurements are approximate; the addition of optional modules will increase the weight

EXTERNAL POWER SUPPLY

65W non-PFC Smart external power adapter; 4.5mm Right Angle 1.8m ,1.0moutput cable
Worldwide auto-sensing 100 - 240 VAC; nominal voltage is 120 VAC; 50 - 60 Hz
Entergy saving automatic power-down; surge tolerant

External power adapters are sourced from several suppliers in order to ensure adequate supply and availability is maintained. The actual dimensions of the power brick will vary by supplier.

HP P/N	Vendor	Dimensions:
P38033-003	Delta	94 x 40 x 26.5 mm
P38033-002	Chicony	95 x 40 x 26.5 mm
P38033-001	Liteon	94 x 39 x 26.5 mm

Technical Specifications

COMPLIANCE/CERTIFICATIONS

Accessibility:	Section 508 Accessibility; VPAT report available.
Environmental Stewardship:	Worldwide (ENERGY STAR®, EPEAT® 2.0, RoHS2, ERP, TCO, CECP& SEPA, HP GSE, WEEE, Low Halogen[1], etc.)
Product Safety:	Worldwide (UL, CB, GS, CCC, BSMI, etc.)
Electromagnetic Compliance (EMC):	Worldwide (FCC/CISPR/EN/VCCI/ICES/AS/NZS/CNS/KCC) "Class B" EMI regulations
Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • US ENERGY STAR®[2] • EPEAT®[3] Silver registered in the United States. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information. • IT ECO declaration

[1]This product is low halogen except for power cords, cables and peripherals; service parts obtained aftermarket may not be low halogen
[2]Configurations of the Product Name Notebook PC that are ENERGY STAR® qualified are identified as Product Name Notebook PC ENERGY STAR on HP websites and on http://www.energystar.gov.
[3] EPEAT® registered where applicable. EPEAT registration varies by country. See www.epeat.net forregistration status by country.

ENVIRONMENTAL

Operating Temperature Range:	50° to 104° F 10° to 40° C	
Non-operating Temperature Range:	-22° to 140° F -30° to 60° C	
Humidity:	Condensing: Non-condensing:	20% to 80% 10% to 90%

NOTE: Specifications are at sea level with altitude derating of 1° C/300m (1.8° F/1000ft) to a maximum of 3 Km (10,000 ft), with no direct, sustained sunlight. Upper limit may be limited by the type and number of options installed.

Energy Consumption (in accordance with US ENERGY STAR® test method)	**115 V ac, 60 Hz**	**230 V ac, 50 Hz**	**100 V ac, 60 Hz**
Normal Operation (Short idle)	4.620	4.620	4.620
Normal Operation (Long idle)	3.036	3.036	3.036
Sleep	0.708	0.708	0.708
Off	0.576	0.576	0.576

Heat Dissipation*	**115 V ac, 60 Hz**	**230 V ac, 50 Hz**	**100 V ac, 60 Hz**
Normal Operation (Short idle)	TBD	TBD	TBD
Normal Operation (Long idle)	TBD	TBD	TBD
Sleep	TBD	TBD	TBD
Off	TBD	TBD	TBD

ETEC 16.97 kWh/per

Technical Specifications

NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.
System configuration includes: Windows 10 IoT Enterprise LTSC 2019 operating system, 256 GB storage, 16 GB of system memory, USB Keyboard and USB Mouse.

ADDITIONAL INFORMATION

• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -2011/65/EC.
• This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
• This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
• This product is in compliance with the IEEE 1680 (EPEAT) standard at the silver level, see http://www.epeat.net.
• Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.
• This product contains 13.9 % post-consumer recycled plastic (by wt.) | Plastic declaration for main chassis is 45% PCR
• This product is 93.4 % recycle-able when properly disposed of at end of life.

Packaging Materials External: PAPER/Corrugated 455 g
Internal: PLASTIC/Polyethylene Expanded - EPE 44 g
PLASTIC/Polyethylene low density - LDPE 5 g

RoHS Compliance HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. By July 1, 2006, RoHS substances will be virtually eliminated (virtually equal to levels below legal limits) for all HP electronic products subject to the RoHS Directive, except where it is widely recognized that there is no technically feasible alternative (as indicated by an exemption under the EU RoHS Directive).

Material Usage
This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):
• Asbestos
• Certain Azo Colorants
• • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics | t540 uses only Low VOC coatings
• Cadmium
• Chlorinated Hydrocarbons
• Chlorinated Paraffins
• Formaldehyde
• Halogenated Diphenyl Methanes
• Lead carbonates and sulfates
• Lead and Lead compounds
• Mercuric Oxide Batteries
• Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
• Ozone Depleting Substances
• Polybrominated Biphenyls (PBBs)
• Polybrominated Biphenyl Ethers (PBBEs)
• Polybrominated Biphenyl Oxides (PBBOs)
• Polychlorinated Biphenyl (PCB)
• Polychlorinated Terphenyls (PCT)
• Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
• Radioactive Substances
• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Technical Specifications

Packaging
HP follows these guidelines to decrease the environmental impact of product packaging:
• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
• Design packaging materials for ease of disassembly.
• Maximize the use of post-consumer recycled content materials in packaging materials.
• Use readily recyclable packaging materials such as paper and corrugated materials.
• Reduce size and weight of packages to improve transportation fuel efficiency.
• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling
HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: https://www.hp.com/us-en/sustainable-impact/planet-product-recycling.html, or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP Inc. web site at:
Disassembly Instructions These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information
For more information about HP's commitment to the environment:
Global Citizenship Report
http://www.hp.com/go/report
Eco-label certifications
https://www.hp.com/us-en/sustainable-impact/document-reports.html#filters_documents_reports-=resource_category-category_ecolabels
ISO 14001 certificates:
http://www.hp.com/go/sustainability_iso14001

Date of change:	Version History:	Type of change	Description of change:
December 17, 2025	From v1 to v2	Correction	“I” added to the platform and document title
February 3, 2026	From v2 to v3	Update	Call out images corrected, number of slots and At a glance section updated
February 18, 2026	From v3 to v4	Removal	HP Anyware PCoIP Client from OS section
February 24, 2026	From v4 to v5	Update	Memory section updated / Links for Product Recycling page, Product Disassembly instructions, Sustainable Impact Report, Eco Labels certification and ISO 14001 in Environmental section updated
March 7, 2026	From v5 to v6	Update	Serial Port added to rear call outs image and 24GB is available on the N97 note added to 24GB in AAG and Memory section where 24GB is.
April 20, 2026	From v6 to v7	Update	24GB removed
September 29, 2026	From v7 to v8	Update	Energy Consumption and ETEC update on Environmental

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